



Product Change Notification

109619 - 00

Information in this document is provided in connection with Intel products. No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document. Except as provided in Intel's Terms and Conditions of Sale for such products, Intel assumes no liability whatsoever, and Intel disclaims any express or implied warranty, relating to sale and/or use of Intel products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right. Intel products are not intended for use in medical, life saving, or life sustaining applications. Intel may make changes to specifications and product descriptions at any time, without notice.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2009. Other names and brands may be claimed as the property of others.

Celeron, Centrino, Intel, the Intel logo, Intel Core, Intel NetBurst, Intel NetMerge, Intel NetStructure, Intel SingleDriver, Intel SpeedStep, Intel StrataFlash, Intel Viiv, Intel XScale, Itanium, MMX, Paragon, PDCharm, Pentium, and Xeon are trademarks or registered trademarks of Intel Corporation or its subsidiaries in the United States and other countries.

Learn how to use Intel Trade Marks and Brands correctly at <http://www.intel.com/intel/legal/tmusage2.htm>.



Product Change Notification

Change Notification #: 109619 - 00
Change Title: Mobile Intel® PM55 Express Chipset, PCN 109619-00, Product Design, B-2 to B-3 Design Conversion
Date of Publication: November 18, 2009

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date of Samples Availability:	Oct 02, 2009
Date of Qualification Data Availability:	Oct 02, 2009
Date of First Availability of Post-Conversion Material:	Dec 07, 2009
Date Customer Must be Ready to Receive Post-Conversion Material:	Feb 16, 2010

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Intel is initiating a B2 to B3 stepping conversion for the Mobile Intel® PM55 Express Chipset, where it will undergo the following changes:

- Change only applies to Mobile products.
- New MM number and S-spec numbers for the converted products.
- B2 and B3 packages are pin compatible.
- Firmware and minor BIOS updates are required with the conversion.
- Processor MRC/microcode update required to enable future processors.
- Recommended storage driver upgrade from Intel® MSM 8.9 to Intel® RST 9.5
- No motherboard modifications required

Customer Impact of Change and Recommended Action:

The B2 to B3 stepping of the Mobile Intel® PM55 Express Chipset is identical in fit, form, electrical, mechanical, and thermal specifications. It is recommended that customers perform their standard validation testing on the new stepping. Customers should be ready to receive a combination of both B2 and B3 stepping material by the "Date Customer Must be Ready to Receive Post-Conversion Material" above. Samples will be available by request.

Products Affected / Intel Ordering Codes:

Marketing Name	Pre Conversion				Post Conversion			
	Product Code	S-Spec	MM#	Stepping	Product Code	S-Spec	MM#	Stepping
Mobile Intel® PM55 Express Chipset	BD82PM55	S LGWN	903212	B-2	BD82PM55	SLH23	904139	B-3

Reference Documents / Attachments:

Document:

Location #:

PCN Revision History:

Date of Revision:

November 18, 2009

Revision Number:

00

Reason:

Originally Published PCN